

Features

- Radial leaded devices
- Smaller size for similar Ihold rating
- Faster tripping
- RoHS compliant*

Applications

- Automotive applications
- Anywhere space is limited and fast tripping is required

MF-RG Series - PTC Resettable Fuses

Electrical Characteristics

Model	V max. Volts	I max. Amps	I_{hold}	I_{trip}	Initial Resistance		1 Hour (R_1) Post-Trip Resistance	Max. Time To Trip		Tripped Power Dissipation
			Amperes at 23 °C		Ohms at 23 °C		Ohms at 23 °C	Amperes at 23 °C	Seconds at 23 °C	Watts at 23 °C
			Hold	Trip	Min.	Max.	Max.			Typ.
MF-RG300	16	100	3.00	5.10	0.038	0.065	0.0975	15	1.0	2.30
MF-RG500	16	100	5.00	8.50	0.015	0.023	0.0340	25	2.0	2.60

Environmental Characteristics

Operating/Storage Temperature	-40 °C to +85 °C	
Maximum Device Surface Temperature in Tripped State	125 °C	
Passive Aging	+85 °C, 1000 hours	±5 % typical resistance change
Humidity Aging	+85 °C, 85 % R.H. 1000 hours	±5 % typical resistance change
Thermal Shock	-40 °C to +85 °C, 10 times	±10 % typical resistance change
Solvent Resistance	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A	No change

Test Procedures And Requirements For Model MF-RG Series

Test	Test Conditions	Accept/Reject Criteria
Visual/Mech.	Verify dimensions and materials	Per MF physical description
Resistance	In still air @ 23 °C	Rmin ≤ R ≤ Rmax
Time to Trip	5 times Ihold, Vmax, 23 °C	T ≤ max. time to trip (seconds)
Hold Current	30 min. at Ihold	No trip
Trip Cycle Life	Vmax, Imax, 100 cycles	No arcing or burning
Trip Endurance	Vmax, 48 hours	No arcing or burning

Thermal Derating Chart - I_{hold} (Amps)

Model	Ambient Operating Temperature								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
MF-RG300	4.4	4.0	3.6	3.0	2.6	2.4	2.1	1.9	1.4
MF-RG500	7.3	6.6	6.0	5.0	4.4	4.0	3.6	3.1	2.4

I_{trip} is approximately two times I_{hold}.

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

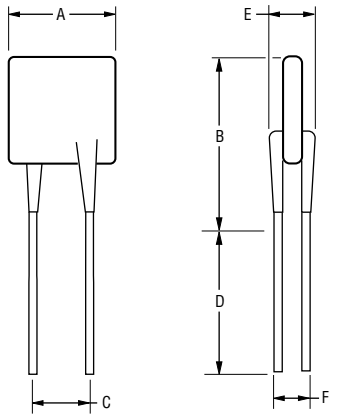
Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.

Product Dimensions

Model	A Max.	B Max.	C Nom.	C Tol. ±	D Min.	E Max.	F Nom.	Physical Characteristics Style	Physical Characteristics Lead Dia.	Physical Characteristics Material
MF-RG300	7.1 (0.280)	11.0 (0.433)	5.1 (0.201)	0.7 (0.028)	7.6 (0.299)	3.0 (0.118)	0.81 (0.032)	1	0.81 (0.032)	Sn/Cu
MF-RG500	10.4 (0.409)	14.3 (0.563)	5.1 (0.201)	0.7 (0.028)	7.6 (0.299)	3.0 (0.118)	0.81 (0.032)	1	0.81 (0.032)	Sn/Cu

Packaging options:
BULK: 500 pcs. per bag. TAPE & REEL: 3000 pcs. per reel. AMMO-PACK: 2000 pcs. per reel.

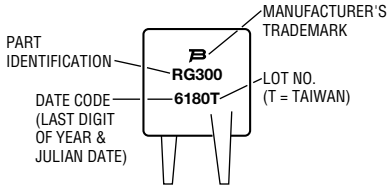
0.81 (20AWG) DIMENSIONS: MM (INCHES)



NOTE: Kinked leads are available for board standoff options. Contact factory for details.

Typical Part Marking

Represents total content. Layout may vary.



How to Order

MF - RG 300 - 0

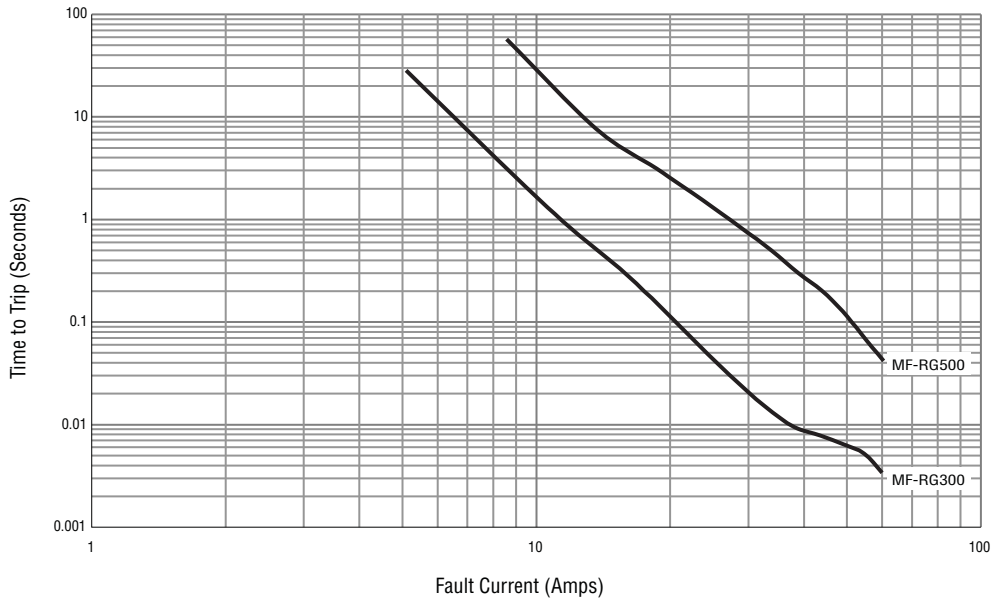
Multifuse® Product Designator

Series
RG = Smaller Radial Leaded Component

Hold Current, Ihold
300-500 (3.0 Amps - 5.0 Amps)

Packaging Options
- 0 = Bulk Packaging
- 2 = Tape and Reel
- AP = Ammo-Pak

Typical Time to Trip at 23 °C



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MF-RG Series Tape and Reel Specifications

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Devices taped using EIA468–B/IEC60286-2 standards. See table below and Figures 1 and 2 for details.

Dimension Description	IEC Mark	EIA Mark	Dimensions	
			Dimensions	Tolerance
Carrier tape width	W	W	18 (.709)	-0.5/+1.0 (-0.02/+.039)
Hold down tape width		W_4	11 (.433)	min.
Hold down tape	W_0		No protrusion	
Top distance between tape edges	W_2	W_6	3 (.118)	max.
Sprocket hole position	W_1	W_5	9 (.354)	-0.5/+0.75 (-0.02/+0.03)
Sprocket hole diameter	D_0	D_0	4 (.157)	±0.2 (±.0078)
Abscissa to plane (straight lead)	H	H	18.5 (.728)	±3.0 (±.118)
Abscissa to plane (kinked lead)	H_0	H_0	16 (.63)	±0.5 (±.02)
Abscissa to top (straight lead)	H_1	H_1	38.0 (1.496)	max.
Abscissa to top (kinked lead)	H_1	H_1	32.2 (1.268)	max.
Overall width w/lead protrusion (straight lead)		C_1	55.0 (2.165)	max.
Overall width w/lead protrusion (kinked lead)		C_1	43.2 (1.7)	max.
Overall width w/o lead protrusion (straight lead)		C_2	54.0 (2.126)	max.
Overall width w/o lead protrusion (kinked lead)		C_2	42.5 (1.673)	max.
Lead protrusion	l_1	L_1	1.0 (.039)	max.
Protrusion of cutout	L	L	11 (.433)	max.
Protrusion beyond hold-down tape	l_2	l_2	Not specified	
Sprocket hole pitch	P_0	P_0	12.7 (0.5)	±0.3 (±.012)
Pitch tolerance			20 consecutive	±1 (±.039)
Device pitch			12.7 (0.5)	
Tape thickness	t	t	0.9 (.035)	max.
Tape thickness with splice		t_1	2.0 (.079)	max.
Splice sprocket hole alignment			4.0 (.157)	±0.2 (±.008)
Body lateral deviation	Δh	Δh	0	±1 (±.039)
Body tape plane deviation	Δp	Δp	0	±1.3 (±.051)
Lead seating plane deviation	ΔP_1	P_1	3.81 (.015)	±0.7 (±.028)
Lead spacing	F	F	8.0 (.315)	
Reel width	w	w	56.0 (2.20)	max.
Reel diameter	d	a	370.0 (14.57)	max.
Space between flanges less device			4.75 (.187)	±3.25 (±.128)

DIMENSIONS: MM (INCHES)

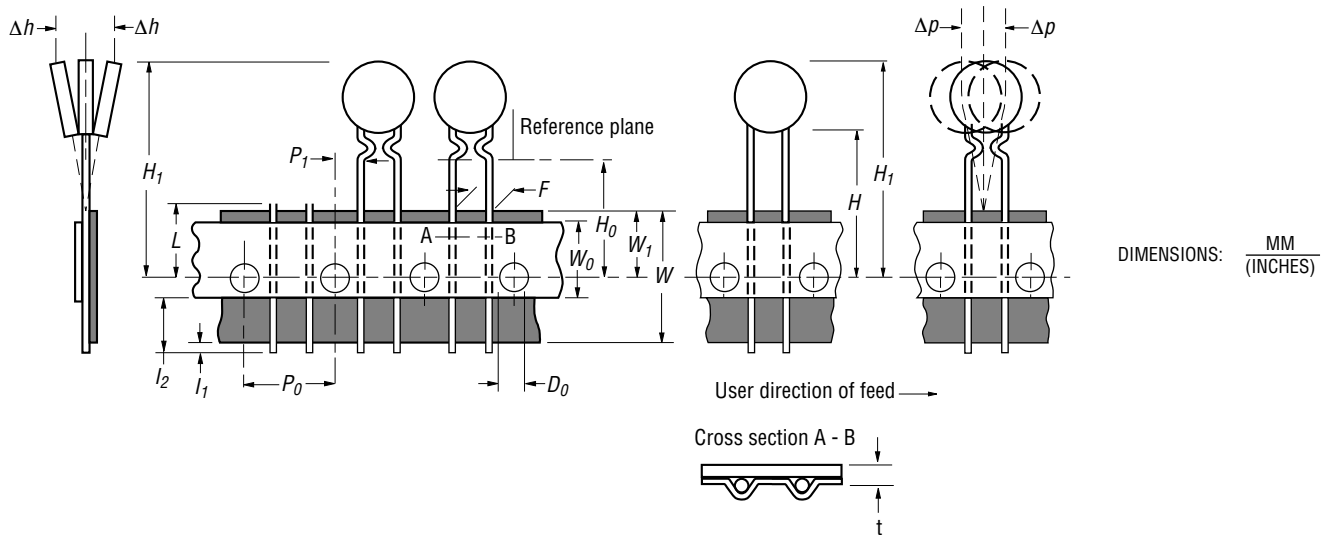
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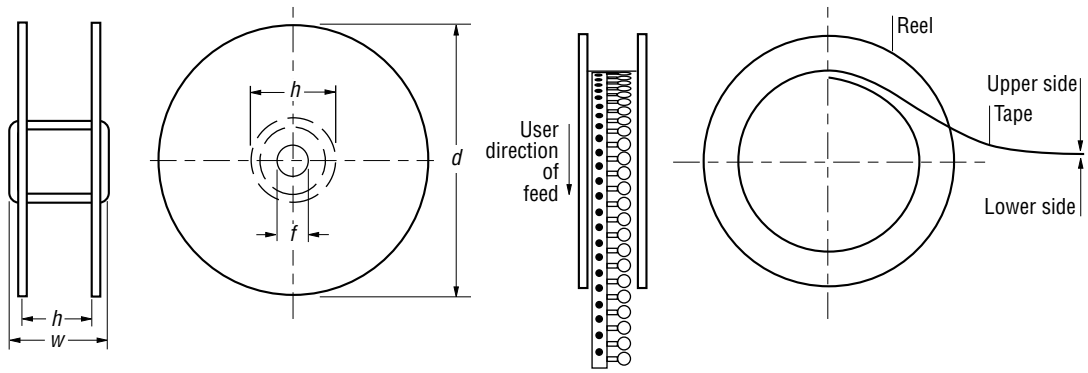
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Dimension Description	IEC Mark	EIA Mark	Dimensions			Tolerance
Arbor hole diameter	*f*	*c*	26.0 (1.02)			±12.0 (±.472)
Core diameter	*h*	*n*	80.0 (3.15)			max.
Box			62 (2.44)	355 (14.0)	345 (13.6)	nom.
Consecutive missing places			3			max.
Empty places per reel			Not specified			

Taped Component Dimensions - Figure 1



Reel Dimensions - Figure 2



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